



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 5, 2008

JFS

Applicants: Atsushi YABE et al

Title: ELECTROLESS COPPER PLATING SOLUTION AND  
ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230

Group: 1792

Confirmation No.: 7180

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/014049

International Filing Date: September 17, 2004

Atty. Docket No.: 4700.P0328US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

Applicant claims small entity status. See 37 CFR 1.27.  
 The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	( ) SM Entity	Fee
Total Claims	(2 - 20 = 0)		x \$ 50.00		x \$ 25.00	
Indep. Claims	(1 - 3 = 0)		x \$210.00		x \$105.00	
[ ] Multiple Dep. Claim			+ \$370.00		+ \$185.00	
* * * TOTAL FILING FEE * * *						\$ 0.00

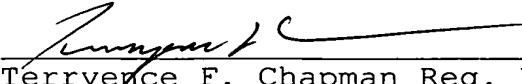
Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

A Check for \$ is enclosed to cover fees.

Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

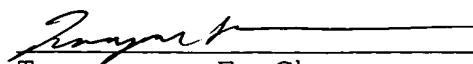
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Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING

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130.09/07

  
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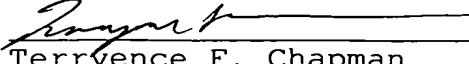
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